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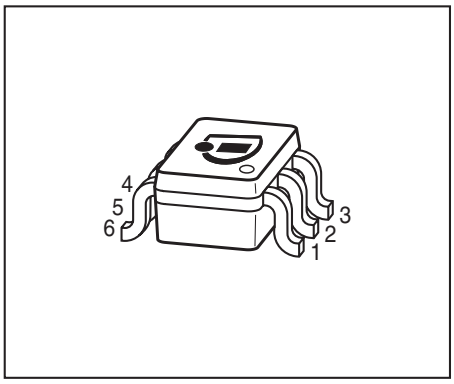
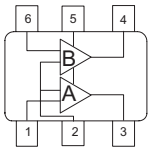
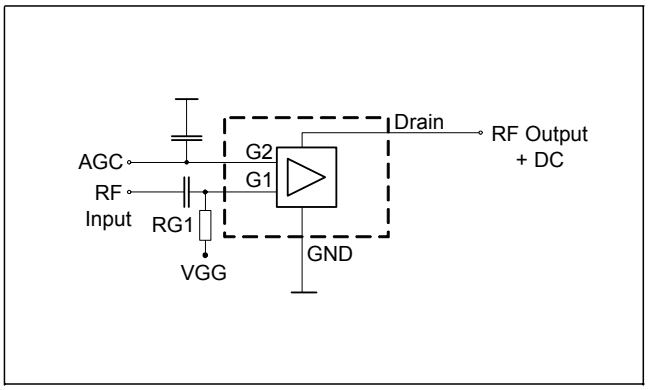
DUAL - N-Channel MOSFET Tetrode



- Low noise gain controlled input stages of UHF-and VHF - tuners with 3V up to 5V supply voltage
- Integrated gate protection diodes
- Low noise figure
- High gain, high forward transadmittance
- Improved cross modulation at gain reduction
- Biasing network partially integrated

BG5130R





ESD (**E**lectro**s**tatic **d**ischarge) sensitive device, observe handling precaution!

Type	Package	Pin Configuration						Marking
BG5130R	SOT363	1=G1*	2=S	3=D*	4=D**	5=G2	6=G1**	KYs

* For amp. A; ** for amp. B

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	8	V
Continuous drain current	I_D	25	mA
Gate 1/ gate 2-source current	$\pm I_{G1/2SM}$	1	
Gate 1/ gate 2-source voltage	$\pm V_{G1/G2S}$	6	V
Total power dissipation $T_S \leq 78$ °C	P_{tot}	200	mW
Storage temperature	T_{stg}	-55 ... 150	°C
Channel temperature	T_{ch}	150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Channel - soldering point[1)]	R_{thchs}	≤ 280	K/W

Electrical Characteristics at T_A = 25°C, unless otherwise specified

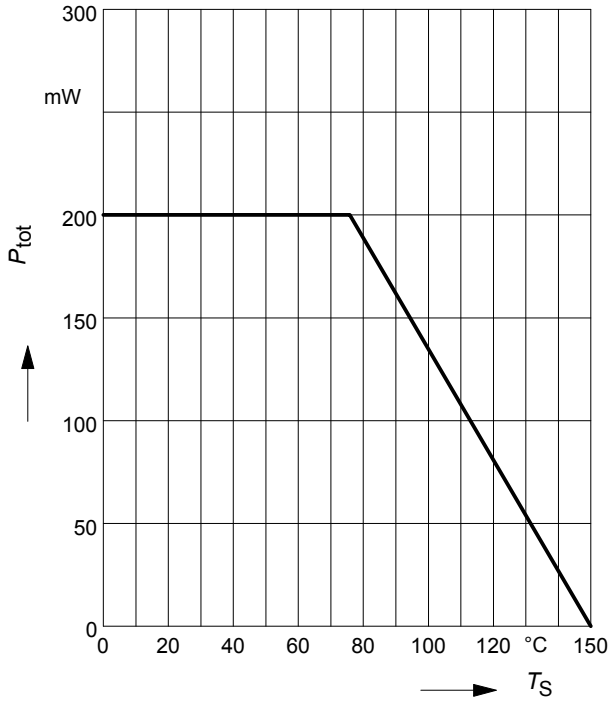
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Drain-source breakdown voltage I_D = 1 µA, V_{G1S} = 0 , V_{G2S} = 0	$V_{(BR)DS}$	12	-	-	V
Gate1-source breakdown voltage +I_{G1S} = 10 mA, V_{G2S} = 0 , V_{DS} = 0	+$V_{(BR)G1SS}$	6	-	15	
Gate2-source breakdown voltage +I_{G2S} = 10 mA, V_{G1S} = 0 , V_{DS} = 0	+$V_{(BR)G2SS}$	6	-	15	
Gate1-source leakage current V_{G1S} = 6 V, V_{G2S} = 0	+I_{G1SS}	-	-	50	nA
Gate2-source leakage current V_{G2S} = 6 V, V_{G1S} = 0 , V_{DS} = 0	+I_{G2SS}	-	-	50	
Drain current V_{DS} = 3 V, V_{G1S} = 0 , V_{G2S} = 3 V	I_{DSS}	-	-	100	
Drain-source current V_{DS} = 3 V, V_{G2S} = 3 V, R_{G1} = 100 kΩ	I_{DSX}	-	10	-	mA
Gate1-source pinch-off voltage V_{DS} = 3 V, V_{G2S} = 3 V, I_D = 20 µA	$V_{G1S(p)}$	-	0.6	-	V
Gate2-source pinch-off voltage V_{DS} = 3 V, V_{G1S} = 3 V, I_D = 20 µA	$V_{G2S(p)}$	-	0.7	-	

[1]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at T_A = 25°C, unless otherwise specified

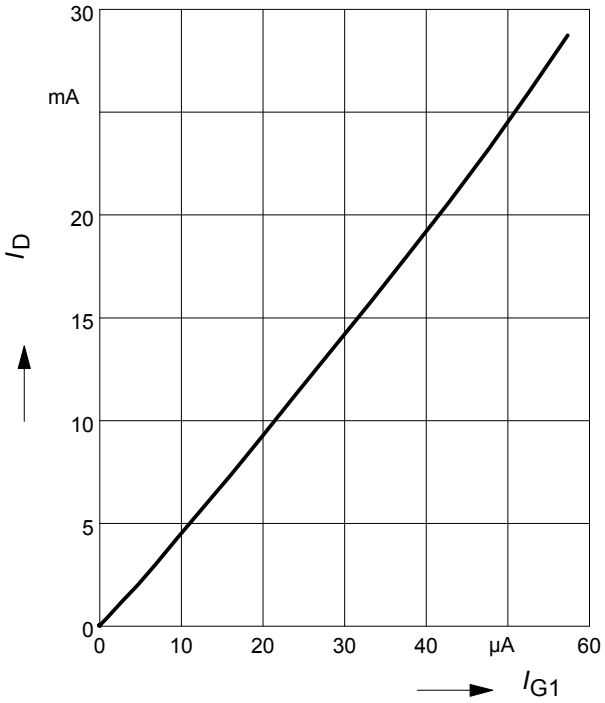
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics - (verified by random sampling)					
Forward transconductance V_{DS} = 3 V, V_{G2S} = 3 V	g_{fs}	-	41	-	mS
Gate1 input capacitance V_{DS} = 3 V, V_{G2S} = 3 V, f = 10 MHz	C_{g1ss}	-	2.7	-	pF
Output capacitance V_{DS} = 3 V, V_{G2S} = 3 V, f = 10 MHz	C_{dss}	-	1.6	-	
Power gain V_{DS} = 3 V, I_D = 10 mA, V_{G2S} = 3 V, f = 800 MHz V_{DS} = 3 V, I_D = 10 mA, V_{G2S} = 3 V, f = 45 MHz	G_p	 - -	 24 35	 - -	dB
Noise figure V_{DS} = 3 V, I_D = 10 mA, V_{G2S} = 3 V, f = 800 MHz V_{DS} = 3 V, I_D = 10 mA, V_{G2S} = 3 V, f = 45 MHz	F	 - -	 1.3 1	 - -	dB
Gain control range V_{DS} = 3 V, V_{G2S} = 3...0 V, f = 800 MHz	ΔG_p	45	-	-	
Cross-modulation k=1%, f_w=50MHz, f_{unw}=60MHz AGC = 0 AGC = 10 dB AGC = 40 dB	X_{mod}	 90 - 96	 94 92 98	 - - -	dB

Total power dissipation $P_{tot} = f(T_S)$

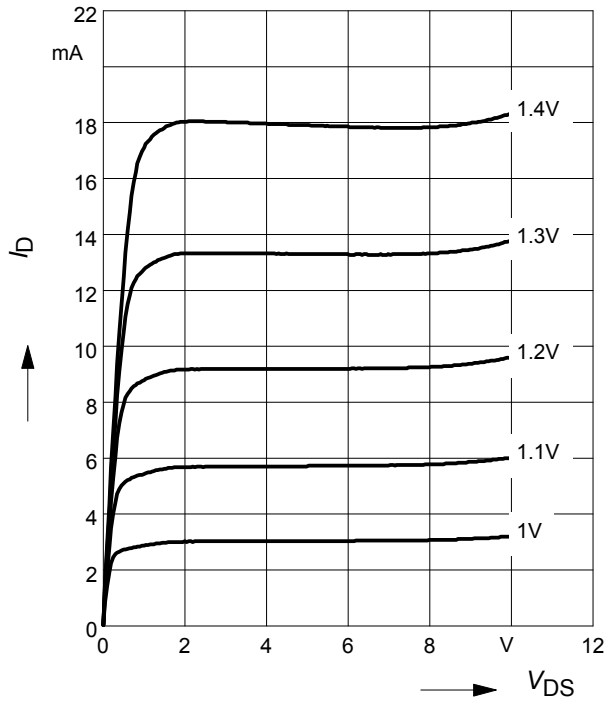


Drain current $I_D = f(I_{G1})$

V_{G2S} = 3V



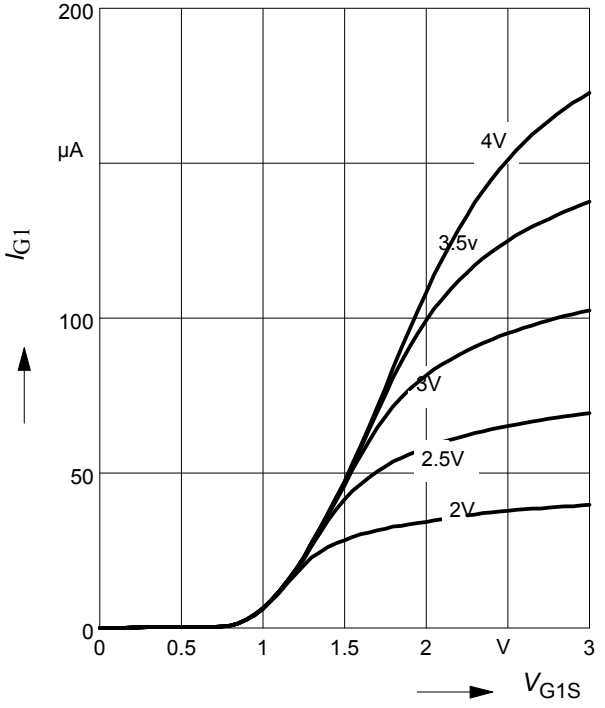
Output characteristics $I_D = f(V_{DS})$



Gate 1 current $I_{G1} = f(V_{G1S})$

V_{DS} = 3V

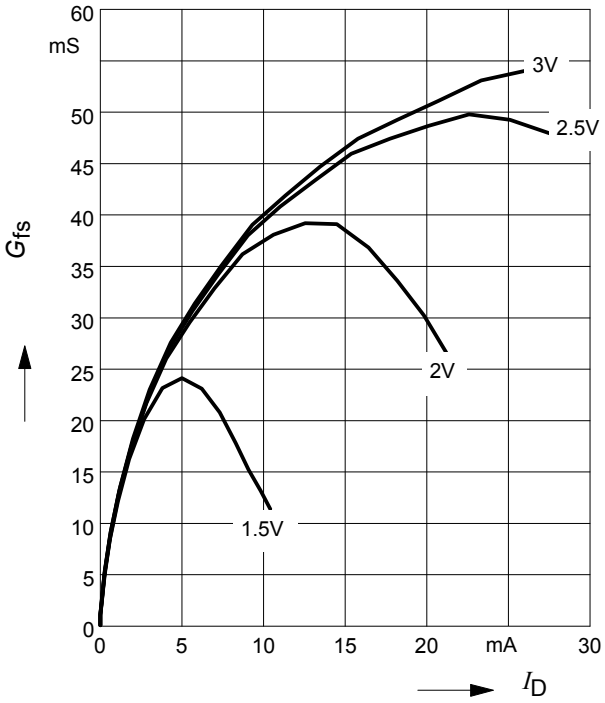
V_{G2S} = Parameter



Gate 1 forward transconductance

$g_{fs} = f(I_D)$

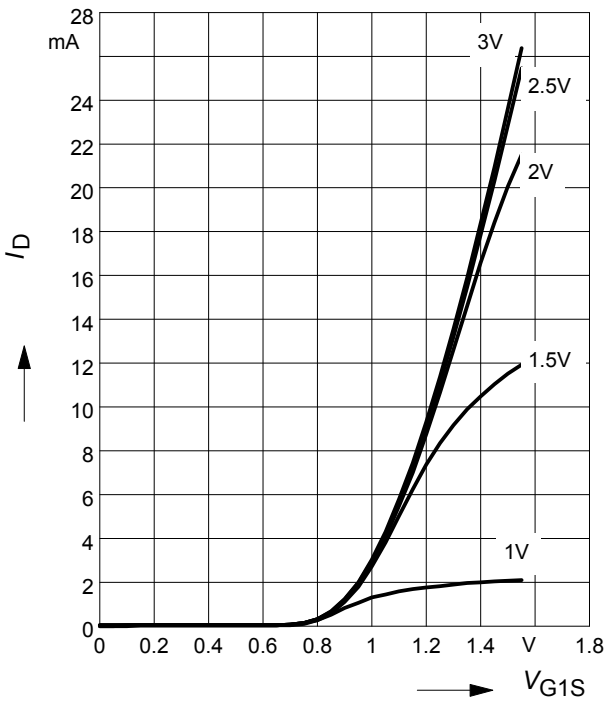
V_{DS} = 3V, V_{G2S} = Parameter



Drain current $I_D = f(V_{G1S})$

V_{DS} = 3V

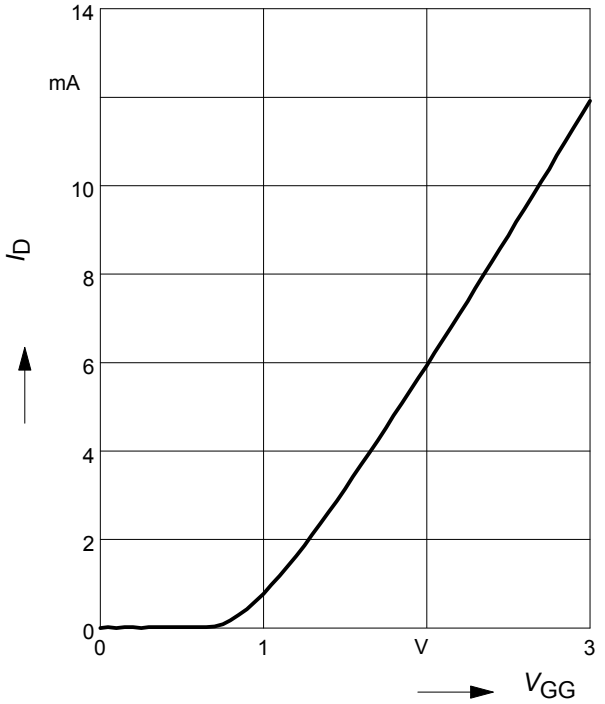
V_{G2S} = Parameter



Drain current $I_D = f(V_{GG})$

V_{DS} = 3V, V_{G2S} = 3V, R_{G1} = 68kΩ

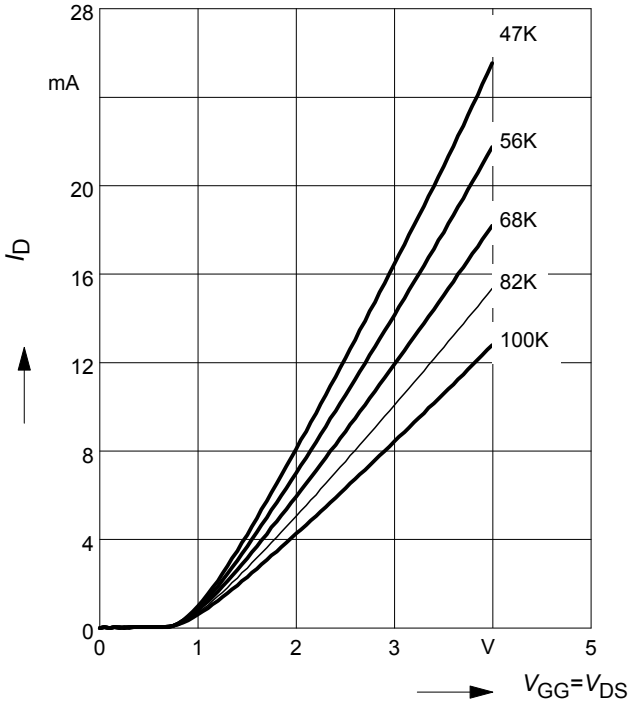
(connected to V_{GG}, V_{GG}=gate1 supply voltage)



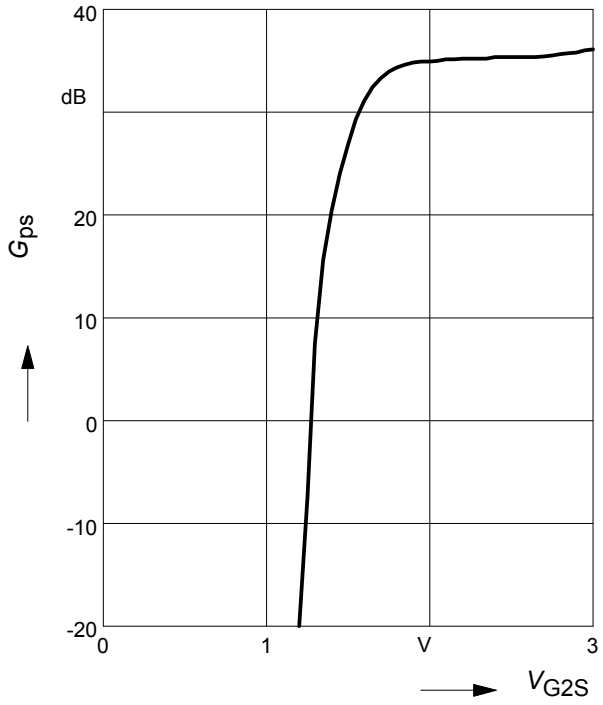
Drain current $I_D = f(V_{GG})$

V_{G2S} = 3V

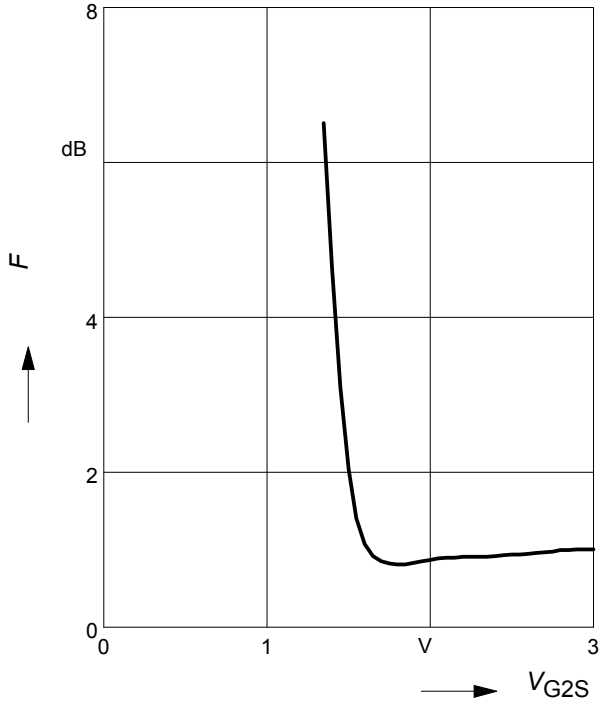
R_{G1} = Parameter in kΩ



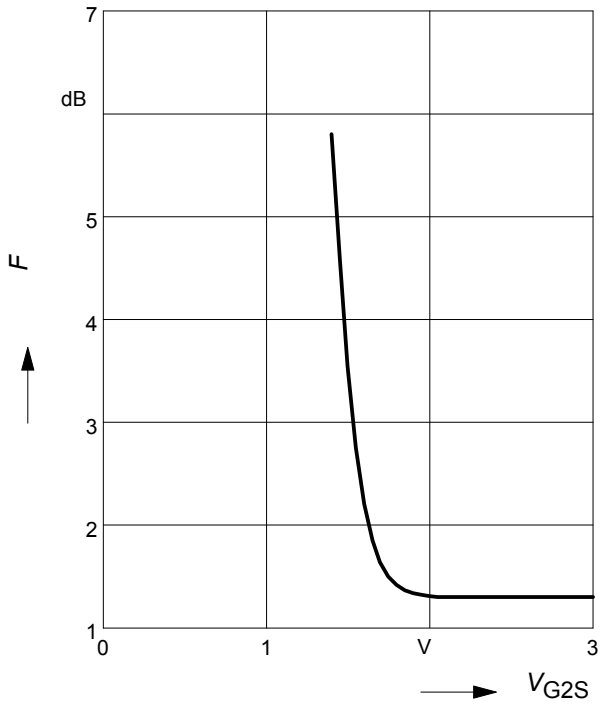
Power gain $G_{ps} = f(V_{G2S})$
f = 45 MHz



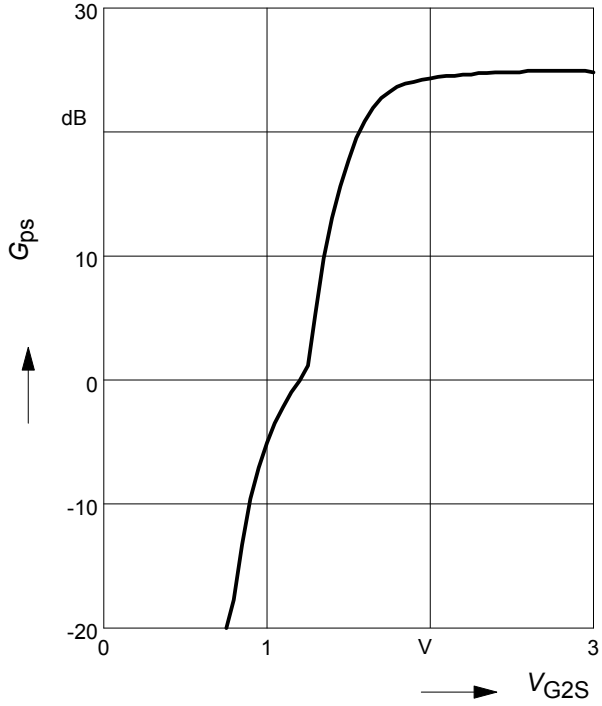
Noise figure $F = f(V_{G2S})$
f = 45 MHz



Noise figure $F = f(V_{G2S})$
f = 800 MHz

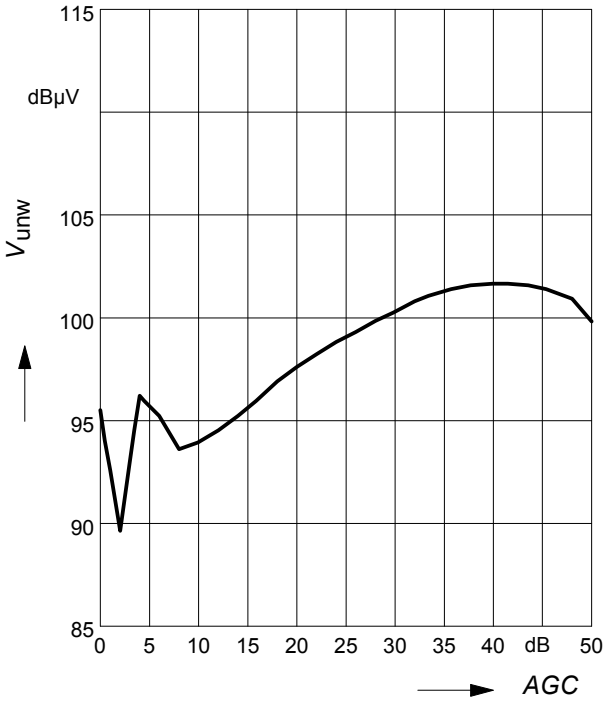


Power gain $G_{ps} = f(V_{G2S})$
f = 800 GHz

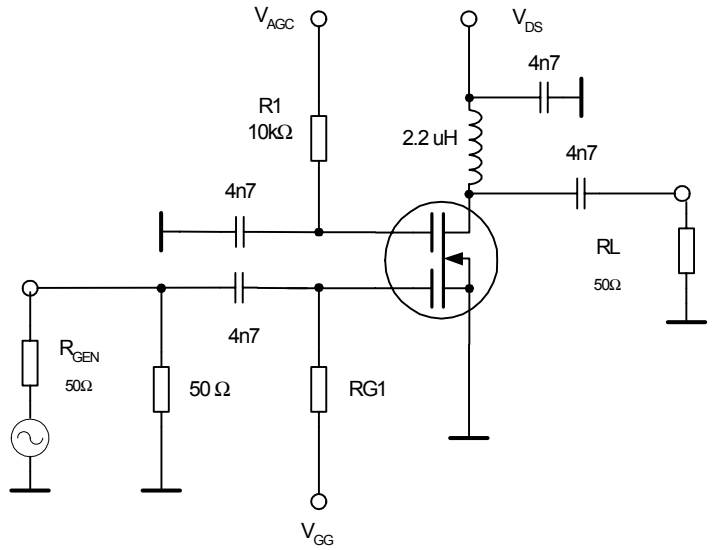


Crossmodulation V_{unw} = (*AGC*)

V_{DS} = 3 V, R_{g1} = 68 kΩ

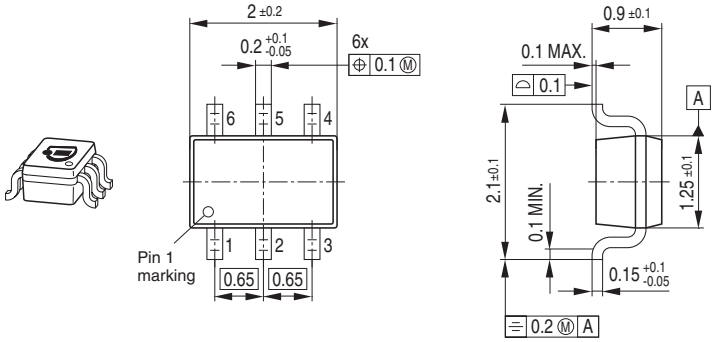


Crossmodulation test circuit

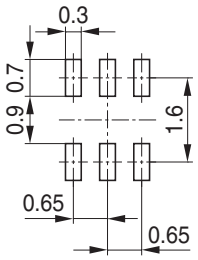


Semibiased

Package Outline

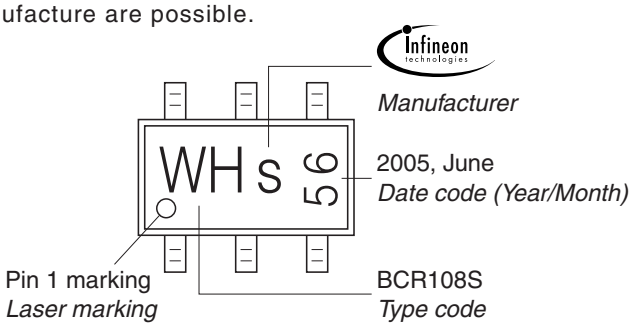


Foot Print



Marking Layout (Example)

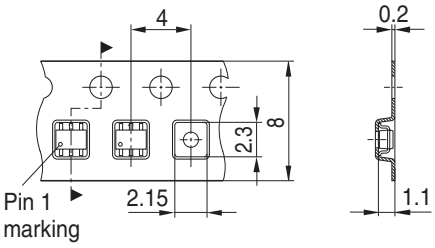
Small variations in positioning of
Date code, Type code and Manufacture are possible.



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



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